

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **05326782 A**

(43) Date of publication of application: **10.12.93**

(51) Int. Cl.

H01L 23/48
// H01L 23/50

(21) Application number: **04128984**

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(22) Date of filing: **21.05.92**

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(54) LEAD FRAME AND SEMICONDUCTOR DEVICE PROVIDED THEREWITH

(57) Abstract:

PURPOSE: To obtain a lead frame which restrains the mismounting of a semiconductor element caused by the bend of leads at positioning and a semiconductor device equipped with the lead frame by a method wherein a lead forming part is lessened in sectional area and curvature so as to enable leads to be easily formed under small stress in a semiconductor forming process.

CONSTITUTION: A lead frame 1 is used in a surface-mounting resin diode, a groove 2 is provided to the lead frame 1 to lessen it in sectional area, and a front groove 2a and a rear groove 2b are formed by punching on both the ends of the groove 2 where leads are bent in an after forming process corresponding to the sealing part 3 of the lead frame 1 when the lead frame 1 is formed through a punching operation.

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